

Eagle Lin

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/1229912/publications.pdf>

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3
papers

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citations

2682572

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2917675

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3
docs citations

3
times ranked

11
citing authors

#	ARTICLE	IF	CITATIONS
1	Fan-Out Panel-Level Packaging of Mini-LED RGB Display. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 739-747.	2.5	8
2	Panel-Level Chip-Scale Package With Multiple Diced Wafers. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1110-1124.	2.5	7
3	Reliability of 6-Side Molded Panel-Level Chip-Scale Packages (PLCSPs). , 2021, , .		3